

IN THE CLAIMS

1. (Previously presented) A gas distribution apparatus for supplying gas into a semiconductor wafer processing chamber, the apparatus comprising:

a body having a bottom wall and a plurality of gas inlets that perforate the bottom wall; and

an injection plate attached to a bottom surface of the bottom wall, the injection plate having grooves on an upper surface of the injection plate that connect the gas inlets, the injection plate also having injection holes that perforate the injection plate at predetermined intervals throughout the grooves.

2. (Previously presented) The apparatus, as defined in claim 1, wherein the gas inlets are formed at different distances from a center of the bottom wall.

3. (Previously presented) The apparatus, as defined in claim 1, wherein the body additionally comprises a plurality of gas inlet extensions that are integral to the bottom wall such that the gas inlets protrude upwardly from the bottom wall.

4. (Previously presented) The apparatus, as defined in claim 1, wherein an external periphery of an upper portion of the body is fastened to the chamber.

5. (Previously presented) The apparatus, as defined in claim 1, wherein the grooves include a ring-shaped groove with a large diameter and a ring-shaped groove with a small diameter.

6. (Previously presented) The apparatus, as defined in claim 1, wherein the injection plate is attached to the bottom wall with a plurality of screws.

7. (Previously presented) A gas distribution apparatus of semiconductor equipment to supply gas into a chamber for a plasma etching process, the apparatus comprising:

a body having a plurality of gas inlets that perforate the body and a cooling water path configured to circulate cooling water inside the body; and

an injection plate attached to a bottom surface of the body, the injection plate having an upper surface with grooves that connect the gas inlets, the injection plate also having injection holes that perforate the injection plate formed at predetermined intervals inside the grooves.

8. (Previously presented) The apparatus, as defined in claim 7, wherein the gas inlets are formed at different distances from the center of a bottom part of the body.

9. (Previously presented) The apparatus, as defined in claim 7, wherein the body additionally comprises a plurality of gas inlet extensions that are integral to the body such that the gas inlets protrude upward from the body.

10. (Previously presented) The apparatus, as defined in claim 7, wherein an external periphery of an upper portion of the body is fastened to the chamber.

11. (Previously presented) The apparatus, as defined in claim 7, wherein the grooves include a ring-shaped groove with a large diameter and a ring-shaped groove with a small diameter.

12. (Previously presented) The apparatus, as defined in claim 7, wherein the injection plate is attached to the bottom surface with a plurality of screws.

13. (Previously presented) The apparatus, as defined in claim 7, wherein the cooling water path includes an injecting hole and a discharging hole.

14. (Previously presented) The apparatus, as defined in claim 13, wherein the injecting and discharging holes protrude upwardly from the bottom part of the body.